WCM4532F-2-102T30

Wire Wound Chip Common Mode Filters

FEATURES

- Winding type realizes small size and low profile
- Prevention of common mode noise at high frequency
- Excellent solderability
- Operating temperature -40~+125℃ (Including self - temperature rise)

APPLICATIONS

- USB2.0 of PC, peripheral equipments, small digital AV equipments, etc.
- LVDS lines of Note PC, LCD
- Audio lines

PRODUCT IDENTIFICATION

WCM 4532 F- 2 - 102 T 30

① ② ③ ④ ⑤ ⑥ ⑦

① Series Name:Wire Wound Chip Common Mode Filters

② Dimensions

③ Feature Type:Ferrite

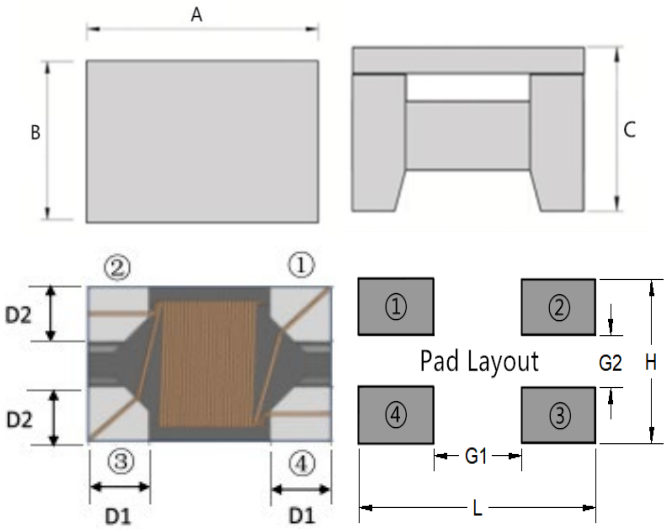
④ Number of Lines 2P=2 lines

⑤ Common Mode Impedance(Ω): 102 = 1000Ω

⑥ Packing: Tape & Reel

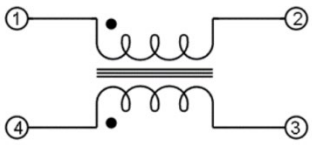
⑦ Rated Current: 30=3000mA

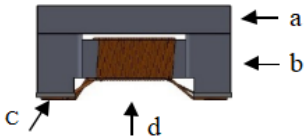
Shapes and Dimensions [Dimensions in mm]



P/N:	WCM4532F-2-102T30
A(mm)	4.5±0.2
B(mm)	3.2.±0.2
C(mm)	2.8±0.2
D1(mm)	0.90
D2(mm)	1.10
G1(mm)	2.70
G2(mm)	0.70
L(mm)	5.1
H(mm)	3.8

Equivalent Circuit / Materials



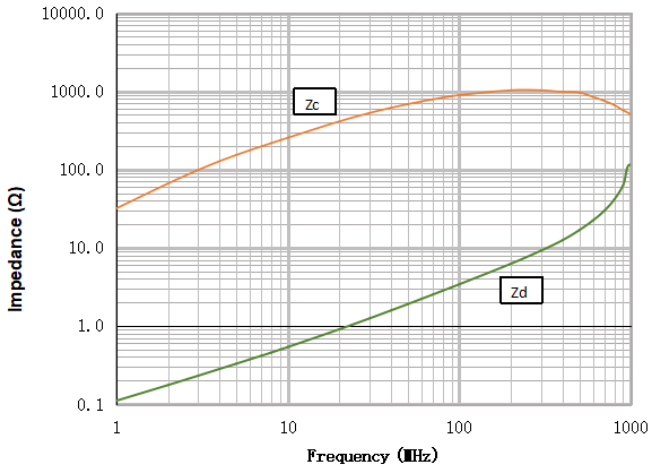


NO.	Description	Specification
a	Upper Plate	Ferrite
b	Core	Ferrite Core
c	Termination	Ag/Ni/Sn
d	Wire	Enameled Copper Wire

Electrical Characterisitics:

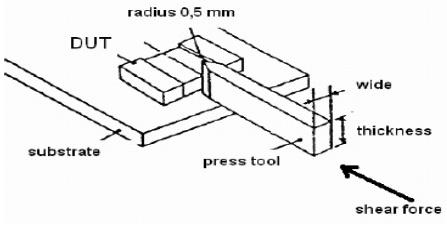
Part No.	Common mode Impedance (Ω)±25%	DC Resistance (Ω) (Max)	Test Frequency (MHz)	Rated Volt. (Vdc)max.	Rated Current (mA)	Withstand Volt. (Vdc)max.	IR (MΩ)min.
WCM4532F-2-102T30	1000	0.055	100	80	3000	125	10

Curve Frequency(MHz)



Reliabily and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Test		
Impedance	Refer to standard electrical characteristics list.	Keysight E4991B + Keysight 16197A
DCR		Agilent-34420A Agilent-4338B
Insulation Resistance	Test Voltage : Rated Voltage Time : 1 minute max.	Chroma 19073
Withstand Volt	Test Voltage : Rated Voltage*2.5 times. Time : 1 ~ 5 s. Charge Current : 1 mA max.	Chroma 19073
Temperature Rise Test	Rated Current ΔT 40℃Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer

<table>
<tr><th colspan="3">Reliability Test</th></tr>
<tr><td>Life Test</td><td rowspan="5">Appearance：No damage.
Impedance：within±15% of initial value
DCR：within±15% of initial value and shall not exceed the specification value</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDECJ-STD-020F Classification Reflow Profiles)
Temperature：125±2℃
Applied current：rated current
Duration：1000±12hrs
Measured at room temperature after placing for 24 hrs.</td></tr>
<tr><td>Load Humidity</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDECJ-STD-020F Classification Reflow Profiles)
Humidity：85±3% RH
Temperature：85℃±2℃
Duration：1000hrs Min.
Bead：with 100% rated current
Inductance：with 10% rated current
Measured at room temperature after placing for 24 hrs.</td></tr>
<tr><td>Moisture Resistance</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDEC J-STD-020F Classification Reflow Profiles)
1. . Ba d at 50℃ for 25hrs, measured at room temperature after placing for 4 hrs.
2. . aise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs.
3. . aise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2hrs then keep at -10℃ for 3hrs.
4. . eep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measured at room temperature after placing for 1~2 hrs.</td></tr>
<tr><td>Thermal Shock</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDEC J-STD-020F Classification Reflow Profiles)
Condition for 1 cycle
Step1：-40±2℃ 30±5min
Step2：125±2℃ ≦0.5min
Step3：125±2℃ 30±5min
Number of cycles：500
Measured at room temperature after placing for 24 hrs.</td></tr>
<tr><td>Vibration</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDEC J-STD-020F Classification Reflow Profiles)
Oscillation Frequency : 10Hz～2kHz～10Hz for 20 minutes
Equipment : Vibration checker
Total Amplitude : 10g
Testing Time : 12 hours (20 minutes, 12 cycles each of 3 orientations)</td></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
DCR：within±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions:
>=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth:
>=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td><table><tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr><tr><td>SMD</td><td>0</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>0</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table>3 shocks in each direction along 3 perpendicular axes. (18 shocks).</td></tr>
<tr><td>Solderability</td><td>More than 95% of the terminal electrode should be covered with solder</td><td>a. Method B, 4hrs @155°C dry heat @235°C±5°C
Testing Time : 5 +0/-0.5 seconds
b. Method D category 3. (8hours ± 15 min)@ 260°C±5°C
Testing Time : 30 +0/-0.5 seconds</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
DCR：within±15% of initial value and shall not exceed the specification value</td><td>Depth: completely cover the termination
<table><tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table></td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through reflow for 3 times.
(IPC/JEDEC J-STD-020F Classification Reflow Profiles)
With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg, <=0805:0.5kg) to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
 
</td></tr>
</table>

Soldering and Mounting

1. Soldering

Mildly activated rosin fluxes are preferred. Magnetsyc terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

1.1 Soldering Reflow:

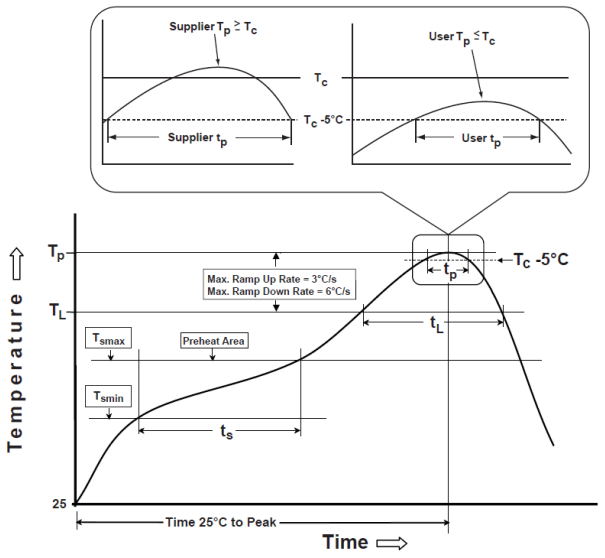
Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020F)

1.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

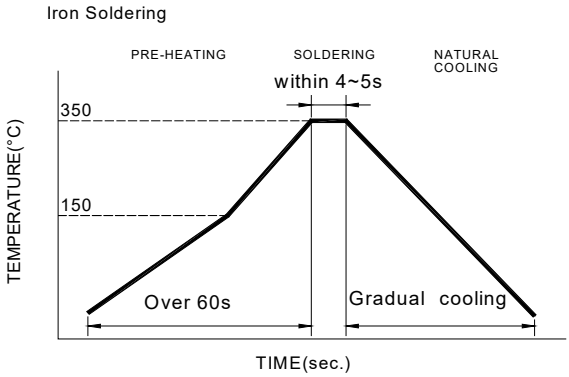
- Preheat circuit and products to 150℃
- 350℃ tip temperature (max)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times：1 times max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	 150℃ 200℃ 60-120seconds
Ramp-up rate($T_L$to T_p)	℃/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217℃ 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at Tc- 5℃ (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate(T_p to T_L)	6℃ /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

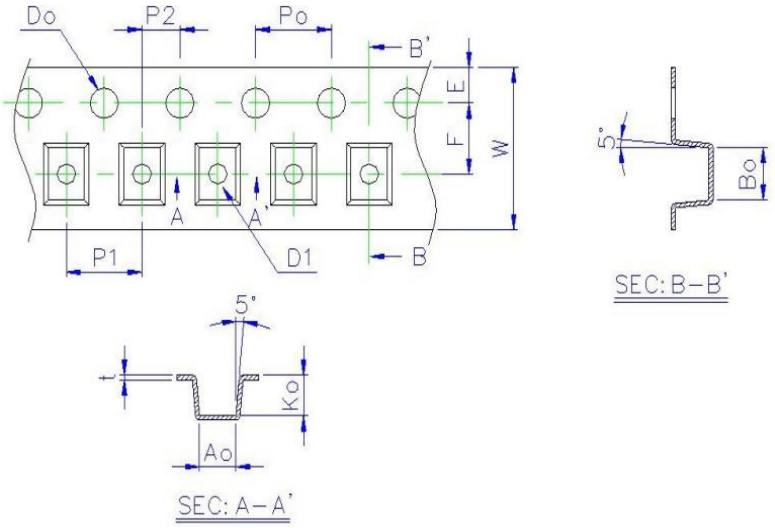
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	℃	260℃	260℃
	1.6-2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

Reflow is referred to standard IPC/JEDEC J-STD-020F

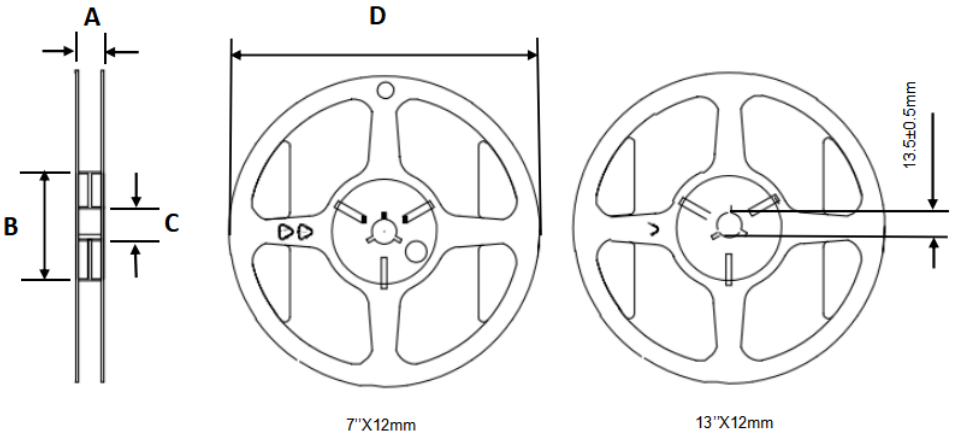
Packaging

(1) Tape Dimensions(Unit:mm)



Size	Ao(mm)	Bo(mm)	Ko(mm)	W(mm)	E(mm)	F(mm)	Po(mm)	P1(mm)	Do(mm)
WCM4532F	3.6±0.10	4.9±0.10	3.0±0.10	12.0±0.10	1.75±0.10	5.50±0.05	4.0±0.05	8.0±0.10	1.5±0.05

(2) Reel



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	13.5 ±0.5	60.0 ±2	13.5 ±0.5	330.0 ±2

Part No.	Tape	MPQ
WCM4532F-2-102T30	Embossed Tape	2000 PCS